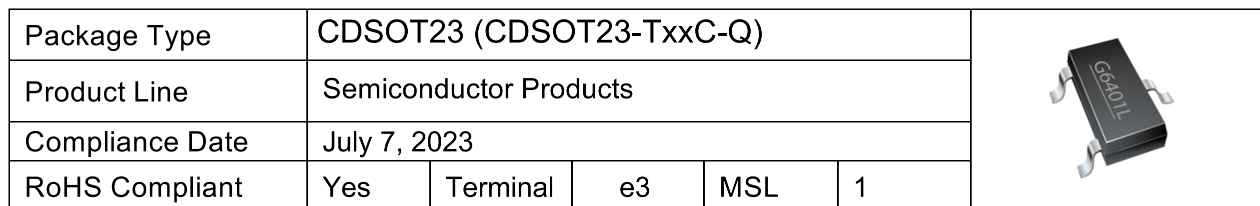
MATERIAL DECLARATION SHEET



Package Type	CDSOT23 (CDSOT23-TxxC-Q)				
Product Line	Semiconductor Products				
Compliance Date	July 7, 2023				
RoHS Compliant	Yes	Terminal	e3	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.005347	Amorphous Silica	60676-86-0	91.69	48.590	52.993
				Epoxy Resin A	Proprietary	4.17	2.208	
				Epoxy Resin B	29690-82-2	1.41	0.749	
				Phenol Resin	Proprietary	2.15	1.137	
				Carbon Black	1333-86-4	0.58	0.309	
2	Leadframe	Copper Alloy	0.003907	Copper	7440-50-8	97.399	37.715	38.722
				Iron	7439-89-6	2.389	0.925	
				Phosphorus	7723-14-0	0.076	0.030	
				Zinc	7440-66-6	0.127	0.049	
				Lead	7439-92-1	0.009	0.003	
		Silver Plating	0.000022	Silver	7440-22-4	100.00	0.218	0.218
3	Chip	Silicon	0.000425	Silicon	7440-21-3	88.374	3.723	4.212
				Nickel	7440-02-0	5.913	0.249	
				Aluminum	7429-90-5	5.347	0.225	
				Gold	7440-57-5	0.366	0.015	
4	Die Attach	Silver Epoxy	0.000088	Silver	7440-22-4	95.190	0.8300	0.872
				Bisphenol-F-(Epichlorhydrin); Epoxy resin	9003-36-5	2.756	0.0241	
				1,4-Bis(2,3-epoxypropoxy) butane	2425-79-8	1.061	0.0093	
				Aromatic polyamine	Proprietary	0.965	0.0084	
				Adipic Acid	124-04-9	0.028	0.0002	
5	Bond Wires	Gold	0.000062	Gold	7440-57-5	99.99	0.6139	0.614
				Non- Au elements	Proprietary	0.010	0.0001	
6	Lead Finish	Matte Tin	0.000239	Tin	7440-31-5	100.00	2.3690	2.369
		Total Weight	0.01009					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.

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